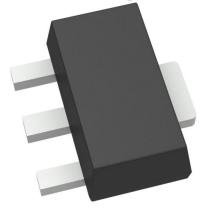


# **FCX558TA Datasheet**

www.digi-electronics.com



DiGi Electronics Part Number	FCX558TA-DG
Manufacturer	Diodes Incorporated
Manufacturer Product Number	FCX558TA
Description	TRANS PNP 400V 0.2A SOT89-3
Detailed Description	Bipolar (BJT) Transistor PNP 400 V 200 mA 50MHz 1 W Surface Mount SOT-89-3

https://www.DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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# Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
FCX558TA	Diodes Incorporated
Series:	Product Status:
-3.02	Active
Transistor Type:	Current - Collector (Ic) (Max):
PNP	200 mA
Voltage - Collector Emitter Breakdown (Max):	Vce Saturation (Max) @ lb, lc:
400 V	500mV @ 6mA, 50mA
Current - Collector Cutoff (Max):	DC Current Gain (hFE) (Min) @ lc, Vce:
100nA	100 @ 50mA, 10V
Power - Max:	Frequency - Transition:
1 W	50MHz
Operating Temperature:	Mounting Type:
-65°C ~ 150°C (TJ)	Surface Mount
Package / Case:	Supplier Device Package:
TO-243AA	SOT-89-3
Base Product Number:	
FCX558	

# **Environmental & Export classification**

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8541.29.0075	





#### **FCX558**

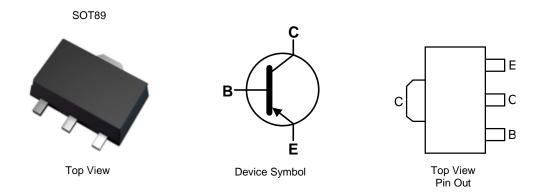
# 400V PNP HIGH VOLTAGE TRANSISTOR IN SOT89

#### **Features**

- $BV_{CEO} > -400V$
- I<sub>C</sub> = -200mA High Continuous Current
- I<sub>CM</sub> = -500mA Peak Pulse Current
- Excellent hFE Characteristics up to -100mA
- Low Saturation Voltage V<sub>CE(sat)</sub> < -200mV @ -20mA
- Complementary NPN Type: FCX458
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT89 •
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.05 grams (Approximate)



### Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
FCX558TA	AEC-Q101	P58	7	12	1,000
Notes: 1. No purposely	added lead. Fully EU Direc	ctive 2002/95/EC (RoHS) & 2	2011/65/EU (RoHS 2) complia	ant.	

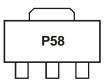
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

## **Marking Information**



P58 = Product Type Marking Code



# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Limit	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-400	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-400	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-200	mA
Peak Pulse Current	I <sub>CM</sub>	-500	mA

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
	(Note 5)		0.7	
Dower Dissignation	(Note 6)	5	1	w
Power Dissipation	(Note 7)	P <sub>D</sub>	1.5	vv
	(Note 8)		2	
	(Note 5)		178	°C/W
Thermal Registeres, Junction to Ambient Air	(Note 6)	R <sub>θJA</sub>	125	
Thermal Resistance, Junction to Ambient Air	(Note 7)		83	
	(Note 8)		60	
Thermal Resistance, Junction to Lead	(Note 9)	R <sub>θJL</sub>	22	
Operating and Storage Temperature Range		TJ, TSTG	-65 to +150	°C

#### ESD Ratings (Note 10)

Notes:

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

5. For a device mounted with the exposed collector pad on minimum recommended pad layout (MRP) 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

Same as Note 5, except the device is mounted with the exposed collector pad on 15mm x 15mm 1oz copper.

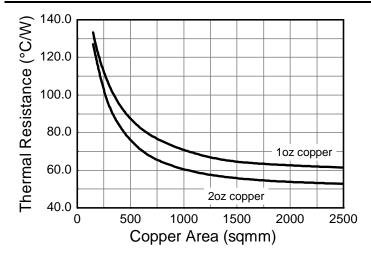
Same as Note 5, except the device is mounted with the exposed collector pad on 25mm x 25mm 1oz copper.
Same as Note 5, except the device is mounted with the exposed collector pad on 25mm x 25mm 1oz copper.

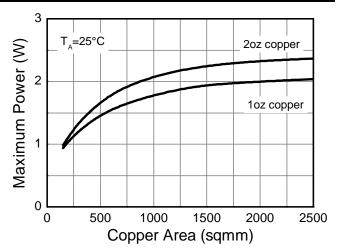
Same as Note 5, except the device is mounted with the exposed collector pad on 20mm x 20mm for copper.
Same as Note 5, except the device is mounted with the exposed collector pad on 50mm x 50mm 1oz copper.

Same as Note 3, except the device is induited with the exposed collector pad on Somm X Somm Y.
Thermal resistance from junction to solder-point (on the exposed collector pad).

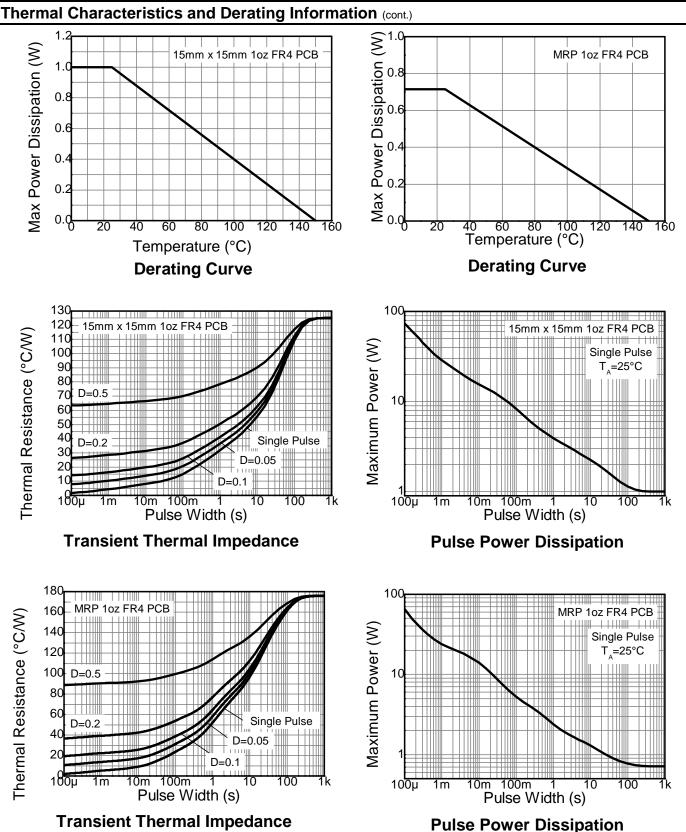
10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## Thermal Characteristics and Derating Information











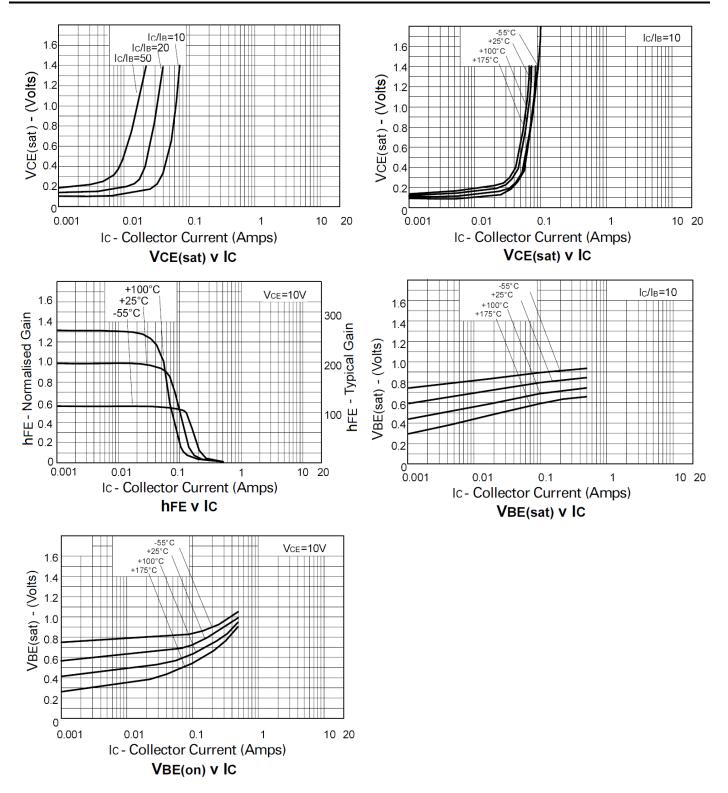
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур.	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-400	-540	-	V	$I_{\rm C} = -100 \mu {\rm A}$
Collector-Emitter Breakdown Voltage (Note 11)	BV <sub>CEO</sub>	-400	-510	-	V	$I_{\rm C} = -1  \text{mA}$
Collector-Emitter Breakdown Voltage	BVCES	-400	-540		V	I <sub>C</sub> = -100μA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.2	-	V	I <sub>E</sub> = -100μA
Collector Cutoff Current	Ісво	-	<-1	-100	nA	V <sub>CB</sub> = -320V
Emitter Cutoff Current	ICES	-	<-1	-100	nA	V <sub>CE</sub> = -320V
Emitter Cutoff Current	I <sub>EBO</sub>	-	<-1	-20	nA	$V_{EB} = -6V$
DC Current Transfer Static Ratio (Note 11)	h <sub>FE</sub>	100 100 15		- 300 -	-	$I_{C} = -1mA, V_{CE} = -10V$ $I_{C} = -50mA, V_{CE} = -10V$ $I_{C} = -100mA, V_{CE} = -10V$
Collector-Emitter Saturation Voltage (Note 11)	V <sub>CE(sat)</sub>	-	-	-0.2 -0.5	V	$I_{C} = -20mA$ , $I_{B} = -2mA$ $I_{C} = -50mA$ , $I_{B} = -6mA$
Base-Emitter Saturation Voltage (Note 11)	V <sub>BE(sat)</sub>	-	-	-0.9	V	$I_{\rm C} = -50 {\rm mA}, I_{\rm B} = -5 {\rm mA}$
Base-Emitter Turn-on Voltage (Note 11)	V <sub>BE(on)</sub>	-	-	-0.9	V	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -10V
Transitional Frequency	f <sub>T</sub>	50	-	-	MHz	I <sub>E</sub> = -10mA, V <sub>CE</sub> = -20V f = 20MHz
Output Capacitance	C <sub>obo</sub>	-	-	5	pF	$V_{CB} = -20V, f = 1MHz,$
Switching Times	t <sub>on</sub> t <sub>off</sub>		95 1,600	-	nS	$I_{C} = -50mA, V_{C} = -100V$ $I_{B1} = -5mA, I_{B2} = -10mA$

Note: 11. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.



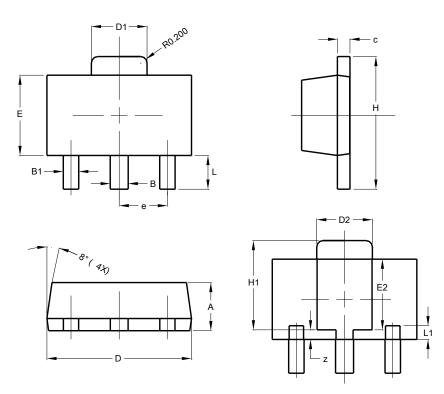
# Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)





# **Package Outline Dimensions**

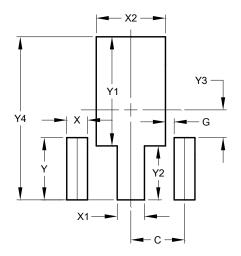
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT89					
Dim	Min	Max	Тур		
Α	1.40	1.60	1.50		
В	0.50	0.62	0.56		
B1	0.42	0.54	0.48		
С	0.35	0.43	0.38		
D	4.40	4.60	4.50		
D1	1.62	1.83	1.733		
D2	1.61	1.81	1.71		
Е	2.40	2.60	2.50		
E2	2.05	2.35	2.20		
е	-	-	1.50		
Н	3.95	4.25	4.10		
H1	2.63	2.93	2.78		
L	0.90	1.20	1.05		
L1	0.327	0.527	0.427		
z	0.20	0.40	0.30		
All	Dimens	sions in	mm		

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	1.500
G	0.244
Х	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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